## **EAST Search History**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	. 210	(@ad<"20011210") and 438/598.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/13 10:14
L2	22	L1 and (etch\$3 near (stop or resistan\$2))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/13 09:41
L3	12	L1 and solder and epoxy	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/13 10:15
L4	199	(@ad<"20011210") and (wafer with ((encapsulant or encapsulat\$3 or epoxy) and scale)) and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/13 09:58
L5	1	("20010040290").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/01/13 09:47
L6	0	l1 and (passivation near epoxy)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/13 09:57
L7		(@ad<"20011210") and wafer and (passivation near epoxy)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/13 10:09

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## **EAST Search History**

L8	15	(@ad<"20011210") and (chip or die) and (passivation near epoxy)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/13 10:09
L9	28	L1 and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/13 10:13
L10	16	L9 not L3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/13 10:13
L11	21830621	(@ad<"20011210") and257/\$.ccls. and (wafer adj scale)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/13 10:14
L12	840	(@ad<"20011210") and "257"/\$.ccls. and (wafer adj scale)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	OFF	2007/01/13 10:15
L13	348	L12 and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	OFF	2007/01/13 10:15
L14	212	L12 and solder and epoxy	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/13 10:15

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